

LINEAR CHEMICAL MECHANICAL PLANARIZATION (CMP) SYSTEM AND METHOD FOR PLANARIZING A WAFER IN A SINGLE CMP MODULE

5

ABSTRACT OF THE DISCLOSURE

A linear chemical mechanical planarization (CMP) belt pad includes a first portion comprised of a first pad material, e.g., polyurethane, and a second portion comprised of a second pad material, e.g., porous rubber. The first portion has a first end and a second end.

10 The second portion is situated between the first and second ends of the first portion and extends substantially across a width of the belt pad. Alternatively, the second portion may be embedded in the first portion such that a peripheral surface of the second portion is surrounded by a surface of the first portion. A linear CMP system and a method for planarizing a wafer in a single linear CMP module also are described.